

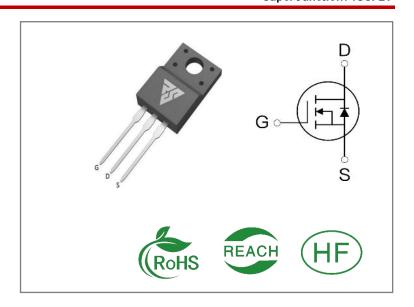
ID	R _{DS} (ON)(Typ)	VDSS
9A	420mΩ	800V

Applications:

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC-DC Switching Power Supply

Features:

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability



Ordering Information

Part Number	Package	Marking	Packing	Qty.
RS80R500F	T0-220F	RS80R500F	Tube	50 PCS

Absolute Maximun Ratings Tc= 25℃ unless otherwise specified

Symbol	Parameter	RS80R500F	Units
VDSS	Drain-to-Source Voltage	800	V
ID	Continuous Drain Current TC=25℃	9	
ID	Continuous Drain Current TC=100℃	5.5	A
IDM	Pulsed Drain Current (Note*1)	27	
PD	Power Dissipation	52	W
VGS	Gate- to- Source Voltage	±30	V
EAS	Single Pulse Avalanche Engergy L=10mH,VDS= 50V, RG = 25 Ω , TC=25 $^{\circ}$ C	270	mJ
dv/dt	MOSFET dv/ dt ruggednessVDS = 0400V	50	V/ns
dv/dt	Reverse diode dv/dt VDS = 0400V, Tj = 25°C, ISD≤ID	15	V/ns
TL TPKG	Maximum Temperature for Soldering Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds	300 260	${\mathbb C}$
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

^{*} Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" Table may cause permanent damage to the device.



Thermal Resistance

Symbol	Parameter	RS80R500F	Units	Test Conditions
RθJC	Junction-to-Case	2.4	°C/W	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of + 1 5 0 $^{\circ}\mathrm{C}$
RθJA	Junction-to- Ambient	67		1 cubic foot chamber,free air.

OFF Characteristics TJ= 25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	800			٧	VGS=0V,ID=250μ A
IDSS	Drain- to- Source Leakage Current			1	μΑ	VDS=800V,VGS= 0V
IGSS	Gate- to- Source Forward Leakage			100	Λ	VGS=30V ,VDS=0 V
1033	Gate- to- Source Reverse Leakage			-100	nA	VGS=-30V ,VDS= 0V

ON Characteristics TJ=25 °C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
RDS(on)	Static Drain- to- Source On- Resistance(Note*2)		420	500	mΩ	VGS=10V,ID=4.5 A
VGS(TH)	Gate Threshold Voltage	2.5		4.5	V	VGS=VDS,ID=25 0μA

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
td(ON)	Turn- on Delay Time		28			
trise	Rise Time		34			VDS=400V
td(OFF)	Turn- OFF Delay Time		100		nS	ID=9A RG=25Ω
tfall	Fall Time		28			



Dynamic Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Ciss	Input Capacitance		1099			VGS=0V
Coss	Output Capacitance		52		pF	VDS=100V
Crss	Reverse Transfer Capacitance		1			f=1.0MHz
Qg	Total Gate Charge		24.6			VDS=400V
Qgs	Gate- to- Source Charge		5.6		nC	ID=9A
Qgd	Gate-to-Drain(" Miller") Charge		9			VGS=10V

Source-Drain Diode Characteristics

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
IS	Continuous Source Current			9	Α	Integral pn- diode
ISM	Maximum Pulsed Current			27	Α	in MOSFET
VSD	Diode Forward Voltage			1.3	V	IS=9A,VGS=0V
trr	Reverse Recovery Time		258		nS	VR=100V
Qrr	Reverse Recovery Charge		3.15		μC	IS=9A,di/dt=100A /µs

Notes:

^{* 1.} Repetitive rating, pulse width limited by maximum junction temperature.

^{* 2.} Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%



Typical Feature Curve

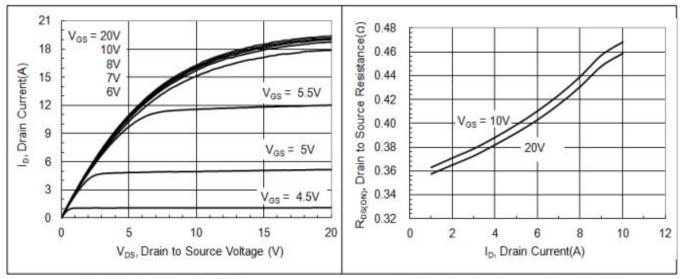


Fig1. Output characteristics

Fig2. Drain-source on-state resistance

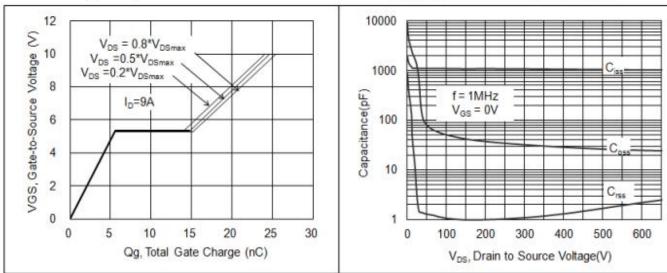


Fig3. Gate charge characteristics

2.8

2.4

2

1.2

0.8

0.4

-80

-40

I_D =4.5A

Roscon, Drain to Source Resistance

(Normalized) 1.6

1.12 Drain to Source Voltage I_D =250uA 1.08 (Normalized) 1.04 0.96 BV_{DS}, 0.92 0.88 -80 -40 0 40 80 120 160 T_J, Junction Temperature (°C)

Fig 4. Capacitance Characteristics

Fig 5. RDS(ON) vs junction temperature

40

T_J, Junction Temperature(°C)

80

120

Fig 6. BVpss vs junction temperature

160



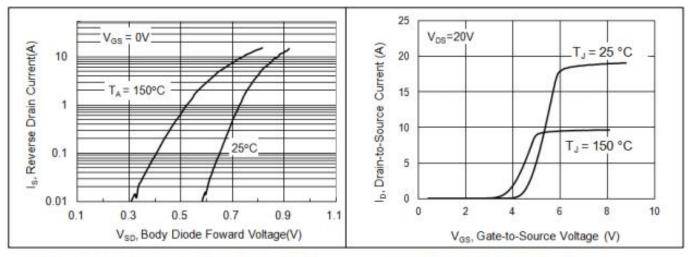


Fig 7. Forward characteristics of reverse diode

Fig 8. Transfer characteristics

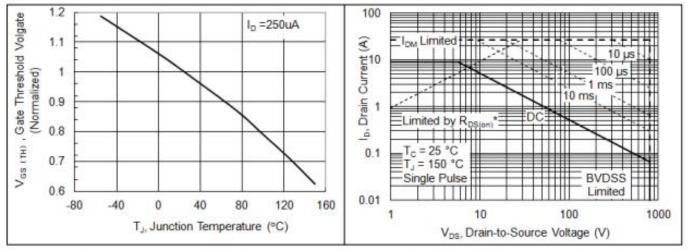


Fig 9. V_{GS(TH)} vs junction temperature

Fig 10. Safe operating area(TO-220F)

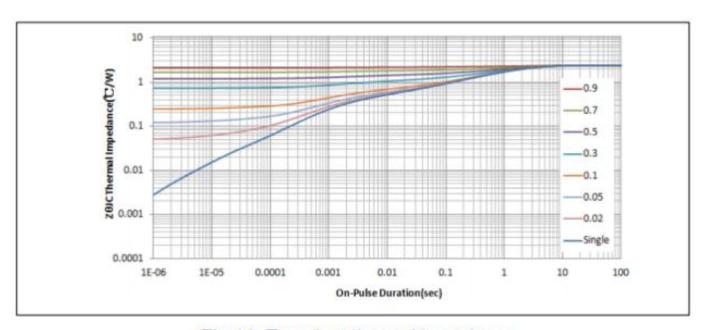


Fig 11. Transient thermal impedance



Test Circuits and Waveforms

Figure A: Gate Charge Test Circuit and Waveform

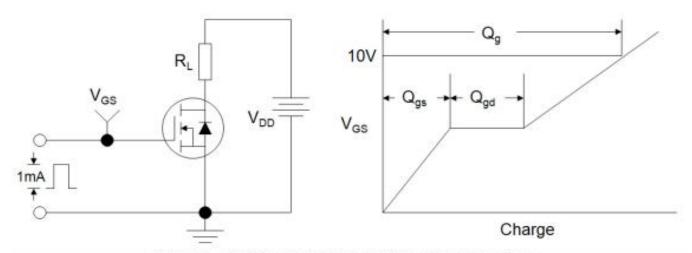


Figure B: Resistive Switching Test Circuit and Waveform

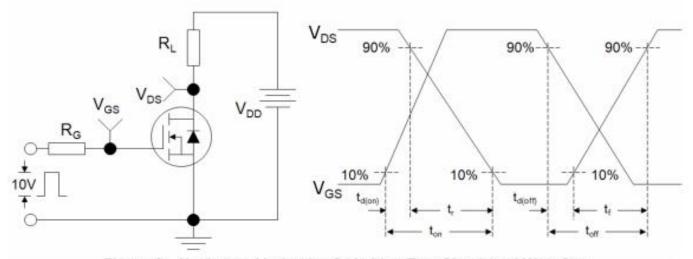
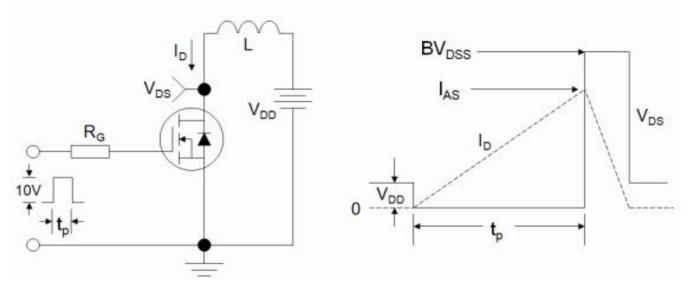
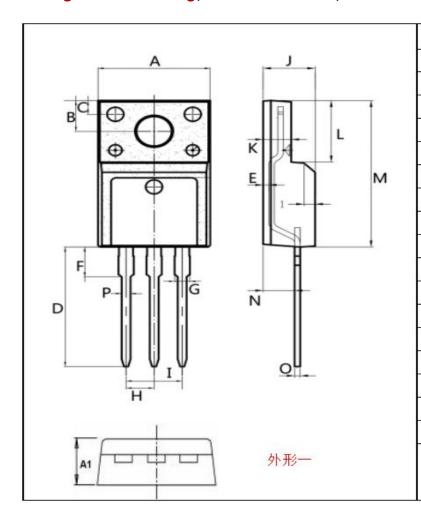


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

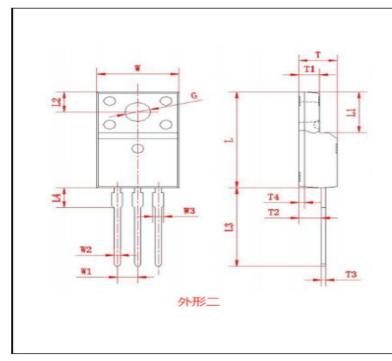




Package outline drawing(TO-220F Unit: mm)



Dim.	Min.	Max.
Α	9.95	10.36
A1	4.5	5.0
В	2.95	3.25
С	1.25	1.45
D	12.60	13.60
E	0.40	0.60
F	2.8	3.5
G	1.30	1.45
Н	(2.54	1)
1	(5.08)	
J	4.60	4.75
K	2.45	2.65
L	6.5	6.8
М	15.4	16.0
N	2.25	3.05
0	0.45	0.55
Р	0.70	0.90



Dim.	Min.	Max.
W	9.95	10.36
W1	(2.5	4)
W2	0.70	0.90
W3	1.25	1.47
L	15.67	16.07
L1	6.48	6.88
L2	3.2	3.4
L3	12.6	13.6
L4	(3.23	3)
Т	4.50	4.90
T1	2.34	2.74
T2	2.25	2.95
Т3	0.45	0.60
T4	(0.	70)
G	3.08	3.28

All Dimensions in millimeter



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DMN1017UCP3-7 EFC2J004NUZTDG P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7
DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 IPS60R360PFD7SAKMA1
DMN2990UFB-7B SSM3K35CT,L3F IPLK60R1K0PFD7ATMA1 2N7002W-G MCAC30N06Y-TP IPWS65R035CFD7AXKSA1
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